

HE2218 Series 500mA Low Power LDO

Features

- Low voltage drop: 0.15V@100mA
- High input voltage: 24V
- Low temperature coefficient
- Large Output Current: >0.5A

Applications

- Portable, Battery Powered Equipment
- Smoke detector and sensor

- Low Quiescent Current: 2.0uA
- Output voltage accuracy: tolerance $\pm 2\%$
- Built-in current limiter
- SOT89-3,SOT89-5,SOT23-3 and SOT23-5 packages
- Audio/Video Equipmen
- Weighting Scales

General Description

The HE2218 series is a group of positive voltage output, three-pin regulators, that provide a high current even when the input/output voltage differential is small. Low power consumption and high accuracy is achieved through CMOS and laser trimming technologies.

The HE2218 consists of a high-precision voltage reference, an error amplification circuit, and a current limited output driver. Transient response to load variations have improved in comparison to the existing series. SOT89-3, SOT89-5,SOT23-3 and SOT23-5 packages are available.

Selection Table

Part No.	Output Voltage	Package	Marking
HE2218A18	1.8V		
HE2218A28	2.8V	SOTO 2	
HE2218A30	3.0V	SOT89-3	
HE2218A33	3.3V	SOT89-5 SOT23-3	Defer to Marking rule
HE2218A36	3.6V	SOT23-5	Refer to Marking rule
HE2218A40	4.0V	50125-5	
HE2218A44	4.4V		
HE2218A50	5.0V		

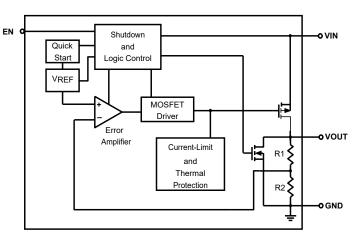
Order Information

HE2218(12)3(4)5

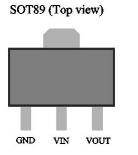
Designator	Symbol	Description
1	A	Standard
23	Integer	Output Voltage(1.8~5.0V)
	Р	Package:SOT89-3
(4)	P5	Package:SOT89-5
	М	Package:SOT23-3
	M5	Package:SOT23-5
(5)	R	RoHS / Pb Free
3	G	Halogen Free



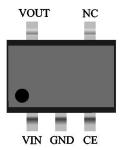
Block Diagram

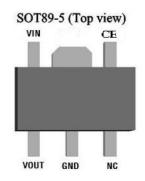


Pin Assignment



SOT23-5 (Top view)





SOT23-3 (Top view)



Absolute Maximum Ratings

Pa	rameter	Symbol	Rating	Unit	
Supply Input Voltage		Vin	-0.3 ~ 24	V	
EN to GND		VEN	-0.3 ~ 24	V	
Regulated Output Volta	age	Vout	-0.3 ~ 6	V	
Output Current		Ιουτ	Internally limited	mA	
	SOT23-3		450		
Power Dissipation	SOT23-5	P _D	500	mW	
P _D @T _A =+25℃	SOT89-3	I D	500	ĨĨĨV	
	SOT89-5		700		
	SOT23-3		275		
Thermal Resistance	SOT23-5	θια	250	∘C /W	
(Junction to air)	SOT89-3		130		
	SOT89-5		125		
Human Body Model (HBM)		4000	V	
Charged Device Mode	(CDM)		2000	V	
Machine Mode (MM)			200	V	
Storage Temperature F	Range	TSTG	-65 ~ +150	°C	
Operating Junction Ter	nperature	TJ	+150	°C	
Lead Temperature (Sol	dering 10s)	TLEAD	+260	°C	

Note:

1. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to absolute-maximum-rated conditions for extended period may affect device reliability.

 $2 \$ Ratings apply to ambient temperature at +25°C

3. The package thermal impedance is calculated in accordance to JESD 51-7.

Recommended Operating Conditions

Item	Min	Max	Unit
Operating Ambient Temperature	-40	+85	°C
Input voltage V _{IN}	2.5	18	V
Output Voltage	1.8	5.0	V



Electronic Characteristics

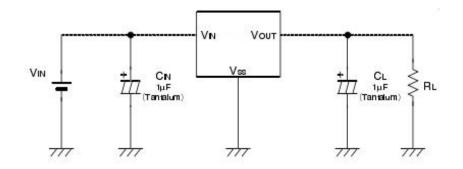
Test Conditions:VIN=VOUT+1V,CIN=COUT=1uF,,TA=25°C, unless otherwise specifi

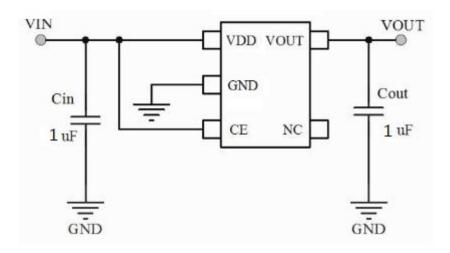
Parameter	Symbol	Condit	ions	Min	Тур	Max	Unit
Input Voltage	VIN			2.5		18	V
Supply Current	lQ	VIN=12V; ILOA	D=0mA		2		uA
Stand-by Current	ISD	EN=0 V; VOUT	=0 V		0	0.2	uA
Output Voltage	Vout	VIN=12V; ILOAD	o =10mA	Vout*0.99		Vout *1.01	V
Output Current	Ιουτ	VIN=VOUT +1V		500			mA
		ILOAD =100mA			150		
Dropout Voltage Vout=3.3V	VDROP	ILOAD =300mA			400		mV
V001-3.3V		ILOAD =500mA			700		
Line Regulation	Δ Vout <i>Ι</i> Δ Vin * Vout	ILOAD =10mA VOUT+1.0V ≦	Vin≦20V		0.05		% / V
Load Regulation	Δ Vout	VIN= VOUT +1∖ 1mA≦ ILOAD ≦			5	20	mV
EN Threshold Valtage	VCEH	CE"High"Voltag	je	1.5			V
EN Threshold Voltage	VCEL	CE"Low"Voltag	e	——		0.4	V
EN PIN Current	IEN				0		uA
Current Limit	ILIMIT			——		750	mA
Short Current	ISHORT	VOUT = GND			100		mA
Output Noise Voltage	Von	COUT =1uF ; IL BW = 10Hz~10			45		uVrмs
Dower Supply		VIN = 4.3V,	f=100Hz		85		dB
Power Supply Rejection Rate	PSRR	Vout =3.3V,	f=1KHz		70		dB
		ILOAD =10mA	f=10KHz		50		dB
Thermal Shutdown Temperature	T _{SHDN}				160		°C
Thermal Shutdown Hysteresis	ΔT_{SHD}				20		°C

Note : All limits specified at room temperature (TA = 25°C) unless otherwise specified. All room temperature limits are 100% production tested. All limits at temperature extremes are ensured through correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).



Typical Application







Application Guideline

Input Capacitor

 $A \ge 1\mu$ F ceramic capacitor is recommended to connect between VIN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both VIN and GND.

Output Capacitor

An output capacitor is required for the stability of the LDO. The recommended output capacitance is $\geq 1\mu$ F, ceramic capacitor is recommended, and temperature characteristics are X7R or X5R. Higher capacitance values help to improve load/line transient response. The output capacitance may be increased to keep low undershoot/overshoot. Place output capacitor as close as possible to VOUT and GND pins.

Dropout Voltage

The dropout voltage refers to the voltage difference between the VIN and VOUT pins while operating at specific output current. The dropout voltage V_{DROP} also can be expressed as the voltage drop on the pass-FET at specific output current (I_{RATED}) while the pass-FET is fully operating at ohmic region and the pass-FET can be characterized as resistance RDS(ON). Thus the dropout voltage can be defined as $(V_{DROP} = V_{IN} - V_{OUT} = R_{DS(ON)} \times I_{RATED})$. Fornormal operation, the suggested LDO operating range is $(V_{IN} > V_{OUT} + V_{DROP})$ for good transient response and PSRR ability. Vice versa, while operating at the ohmic region will degrade the performance severely.

Thermal Application

For continuous operation, do not exceed the absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated as below:

 T_A =25°C, AISIS DEMO PCB, The max P_D = (Tj – T_A) / θ_{JA} .



Power dissipation (P_D) is equal to the product of the output current and the voltage drop across the output pass element, as shown in the equation below:

 $\mathsf{P}_{\mathsf{D}} = (\mathsf{V}_{\mathsf{IN}} - \mathsf{V}_{\mathsf{OUT}}) \times \mathsf{I}_{\mathsf{OUT}}$

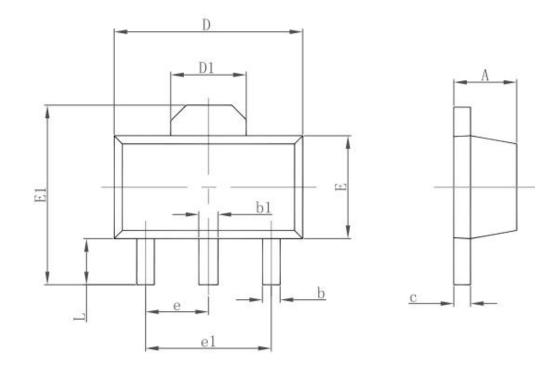
Layout Consideration

By placing input and output capacitors on the same side of the PCB as the LDO, and placing them as close as is practical to the package can achieve the best performance. The ground connections for input and output capacitors must be back to the HE2218 ground pin using as wide and as short of a copper trace as is practical.Connections using long trace lengths, narrow trace widths, and/or connections through via must be avoided. These add parasitic inductances and resistance that results in worse performance especially during transient conditions.



HE2218 Series 500mA Low Power LDO

Package Information 3-pin SOT89 Outline Dimensions

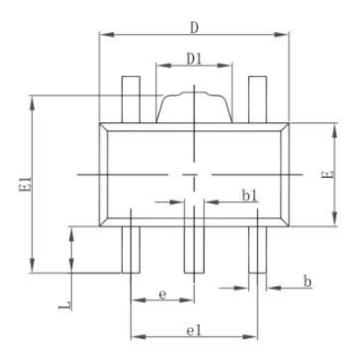


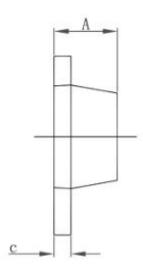
Combal	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
С	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550	REF.	0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
е	1.500 TYP.		0.060	TYP.
e1	3.000 TYP.		0.118	3 TYP.
L	0.900	1.200	0.035	0.047



HE2218 Series 500mA Low Power LDO

SOT89-5 Outline Dimensions

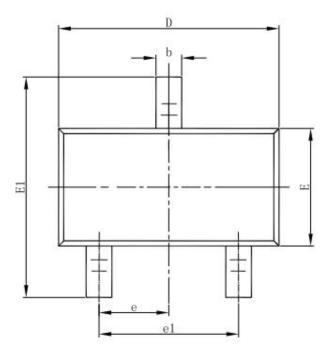


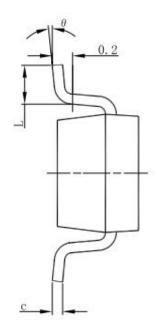


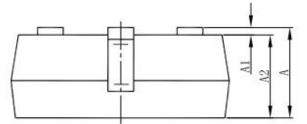
C. make al	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.360	0.560	0.014	0.022
С	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.400	1.800	0.055	0.071
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
е	1.500TYP.		0.060	TYP.
e1	2.900	3.100	0.114	0.122
L	0.900	1.100	0.035	0.043



3-pin SOT23-3 Outline Dimensions



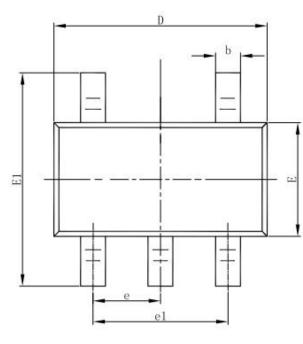


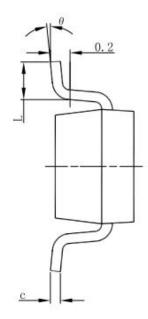


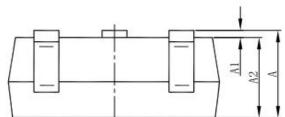
Sumb a l	Dimensions In	Millimeters	Dimensions I	n Inches
Symbol	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
е	0.950(BSC)	0.037(B	SC)
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°



SOT23-5 Outline Dimensions







0	Dimensions In	Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
е	0.950(BSC)	0.037(BSC)
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°